



# E-beam Evaporator

Prepared by  
Yimin Zhou / Henry Lee

# Vacuum

- Pressure units

atmosphere	Torr	bar	pascals
1	760	1	$101 \times 10^3$

1 Torr  $\sim$  1/760 atm  $\sim$  1/1000 atm = 1 mbar

- In Chamber

$$10^{-5} \text{ mbar} = 10^{-5} \text{ Torr}$$

Use a cryogenic pump

- Pumping sequence

Rough pump atm  $\rightarrow$  0.01 mbar in <15min

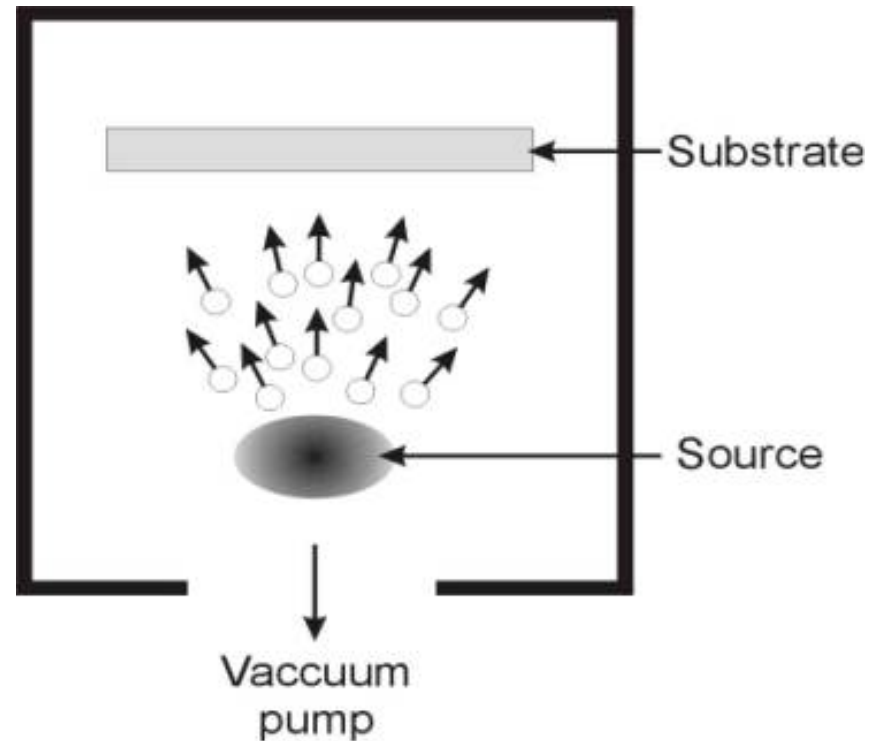
Cryopump  $\rightarrow 10^{-5 / -6}$  mbar in about 1hr

# BOC Edwards A306 Evaporator



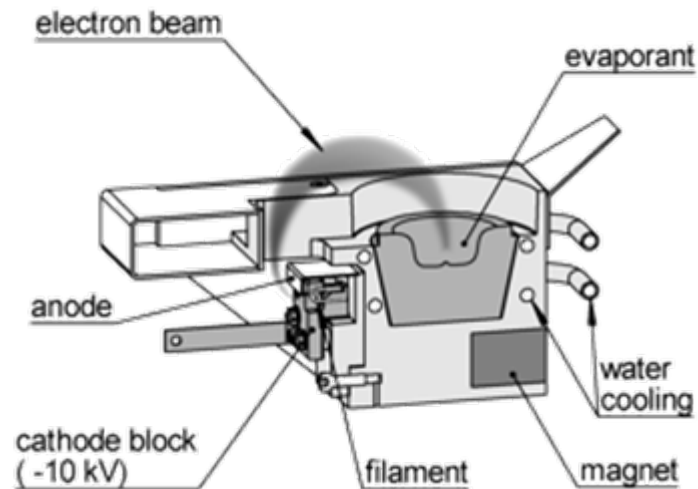
# Technique

- Vacuum chamber at  $10^{-5}$  mbar
- Use a beam of electrons to melt metal (source)
- Vapor deposits onto sample (substrate)



## ■ Principle of e-beam evaporator operation

- The electron emitter is designed with 270° beam deflection
- Temperature ~ electron current

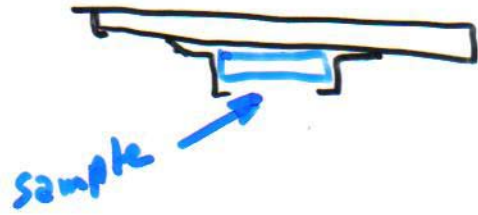


## Melting, Boiling Points

Metal	Melting point (°C)	Boiling point (°C)
Al	660	2500
Au	1062	2800
Ti	1657	2600
Cr	1890	3200
W	3410	5500

Cost: per 50 gm

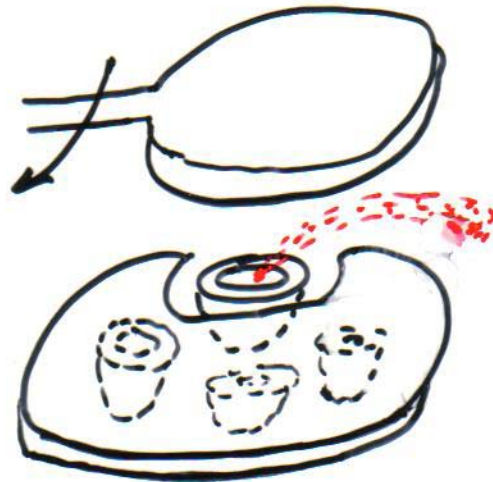
Metal	Price (CAD)
Al	\$25
Cr	\$50
Au	\$1300, now?
Pt	\$2600



sample holder



thickness monitor



Shutter

four crucibles



# Thickness Monitor

- Metal deposited →  
Frequency change →

Constants (density,  
acoustic imped. “Z”,  
“Tooling”)

→ Thickness

→ “Tooling” is a solid angle correction factor  
calculated with geometric formulae



## Notes :

1. Evaporator is for approved metals only. Some metals are toxic. Some are reactive and will foul the cryopump resulting in expensive repair.
2. Typical pressure during evaporation is 1 to 3 x 10<sup>-5</sup> mbar range.
3. Do not run electron gun if pressure is greater than 6 x 10<sup>-5</sup> mbar (filament will burn out).
4. Very gradually/slowly increase electron current. The pressure will increase due to absorbed water vapor, adsorbed air being heated off all the surfaces inside the chamber.
5. Do not run for more than 30 minutes at currents greater than 250 mA.
6. Each metal requires a special crucible material (graphite, carbon, refractory, intermetallic).
7. Crucibles are about 2 cc volume. Fill 0.6 to 0.8 only.

8. Typical deposition rate is 0.1 nm/sec
9. If sample is put closer to source, evaporation is faster but uniformity is worse for a large sample and sample will get hotter.
10. There is no sample cooling so doing a long, hot evaporation will make the sample get hot.
11. Evaporated films more than 1 micron take a long time, uses lots of source metal and will have adhesion, stress problems.
12. Cross contamination (from other metals) : inspect the lip near the crucible.
13. See [www.lesker.com](http://www.lesker.com) and <http://www.ee.byu.edu/cleanroom/metal.phtml> for tables on metals, evaporation rates, etc.